



# PMEG4005CT

500 mA low VF dual MEGA Schottky barrier rectifier

24 September 2019

Product data sheet

## 1. General description

Planar Maximum Efficiency General Application (MEGA) Schottky barrier rectifier in common cathode configuration with an integrated guard ring for stress protection, encapsulated in a SOT23 (TO-236AB) small Surface-Mounted Device (SMD) plastic package.

## 2. Features and benefits

- Average forward current:  $I_{F(AV)} \leq 0.5$  A
- Reverse voltage:  $V_R \leq 40$  V
- Small SMD plastic package
- Low forward voltage
- AEC-Q101 qualified

## 3. Applications

- Low voltage rectification
- Reverse polarity protection
- High efficiency DC-to-DC conversion
- High-speed switching
- Switch Mode Power Supply (SMPS)
- Low power consumption applications

## 4. Quick reference data

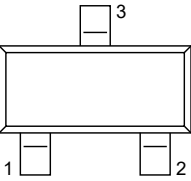
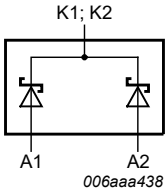
Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Per diode</b>						
$I_{F(AV)}$	average forward current	square-wave pulse; $\delta = 0.5$ ; $f = 20$ kHz; $T_{amb} \leq 85$ °C	[1]	-	0.5	A
		square-wave pulse; $\delta = 0.5$ ; $f = 20$ kHz; $T_{sp} \leq 130$ °C		-	0.5	A
$V_R$	reverse voltage	$T_j = 25$ °C	-	-	40	V
$V_F$	forward voltage	$I_F = 500$ mA; $T_j = 25$ °C	-	410	470	mV
$I_R$	reverse current	$V_R = 40$ V; $T_j = 25$ °C	-	27	100	$\mu$ A

[1] Device mounted on a ceramic PCB,  $Al_2O_3$ , standard footprint.

## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	A	anode (diode 1)	 <p style="text-align: center;"><b>SOT23</b></p>	 <p style="text-align: center;">006aaa438</p>
2	A	anode (diode 2)		
3	K1, K2	common cathode (diode 1 and diode 2)		

## 6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PMEG4005CT	SOT23	plastic, surface-mounted package; 3 terminals; 1.9 mm pitch; 2.9 mm x 1.3 mm x 1 mm body	SOT23

## 7. Marking

Table 4. Marking codes

Type number	Marking code <sup>[1]</sup>
PMEG4005CT	PA%

[1] % = placeholder for manufacturing site code

## 8. Limiting values

**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
<b>Per diode</b>						
$V_R$	reverse voltage	$T_j = 25\text{ °C}$		-	40	V
$I_{F(AV)}$	average forward current	square-wave pulse; $\delta = 0.5$ ; $f = 20\text{ kHz}$ ; $T_{amb} \leq 85\text{ °C}$	[1]	-	0.5	A
		square-wave pulse; $\delta = 0.5$ ; $f = 20\text{ kHz}$ ; $T_{sp} \leq 130\text{ °C}$		-	0.5	A
$I_{FRM}$	repetitive peak forward current	$t_p \leq 1\text{ ms}$ ; $\delta \leq 0.25$		-	3.9	A
$I_{FSM}$	non-repetitive peak forward current	square-wave pulse; $t_p = 8\text{ ms}$ ; $T_{j(init)} = 25\text{ °C}$		-	10	A
<b>Per device; one diode loaded</b>						
$P_{tot}$	total power dissipation	$T_{amb} \leq 25\text{ °C}$	[2]	-	330	mW
			[3]	-	400	mW
			[1]	-	460	mW
$T_j$	junction temperature			-	150	°C
$T_{amb}$	ambient temperature			-55	150	°C
$T_{stg}$	storage temperature			-65	150	°C

[1] Device mounted on a ceramic PCB,  $Al_2O_3$ , standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode  $1\text{ cm}^2$ .

## 9. Thermal characteristics

**Table 6. Thermal characteristics**

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1] [2]	-	-	375	K/W
			[1] [3]	-	-	310	K/W
			[1] [4]	-	-	270	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		[1] [5]	-	-	60	K/W

[1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses  $P_R$  are a significant part of the total power losses.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode  $1\text{ cm}^2$ .

[4] Device mounted on a ceramic PCB,  $Al_2O_3$ , standard footprint.

[5] Soldering point of cathode tab.

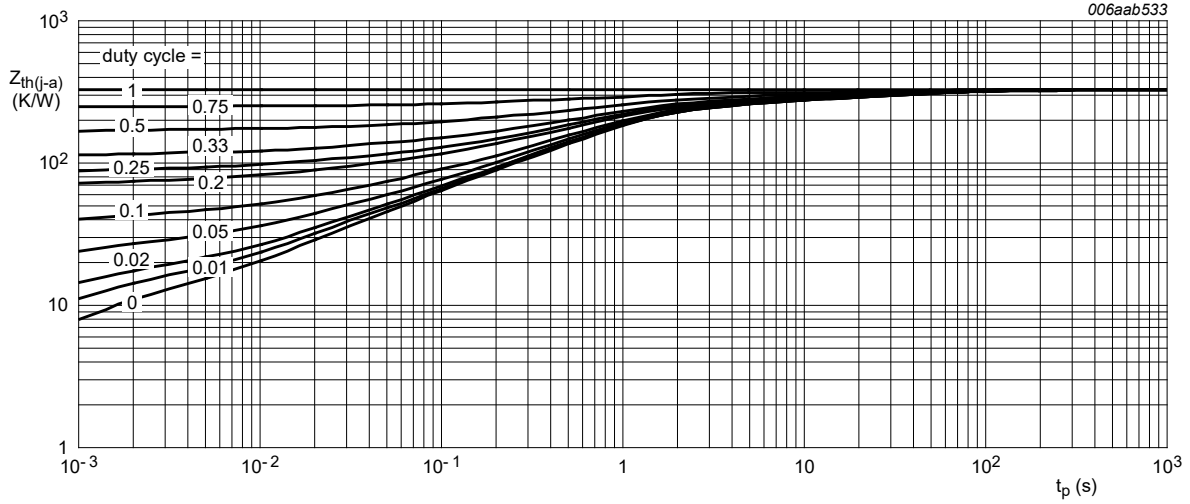


Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

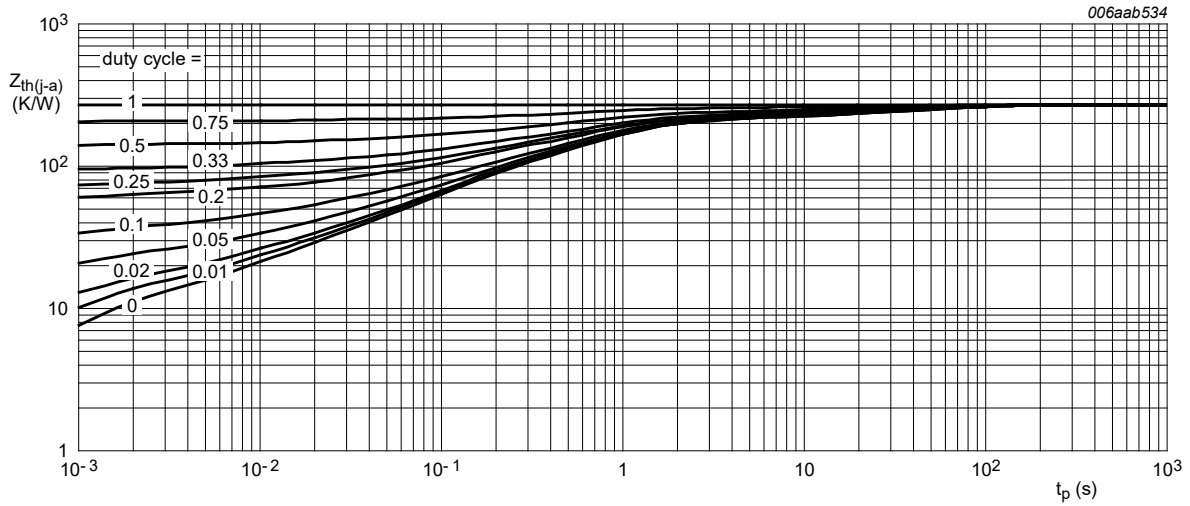


Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

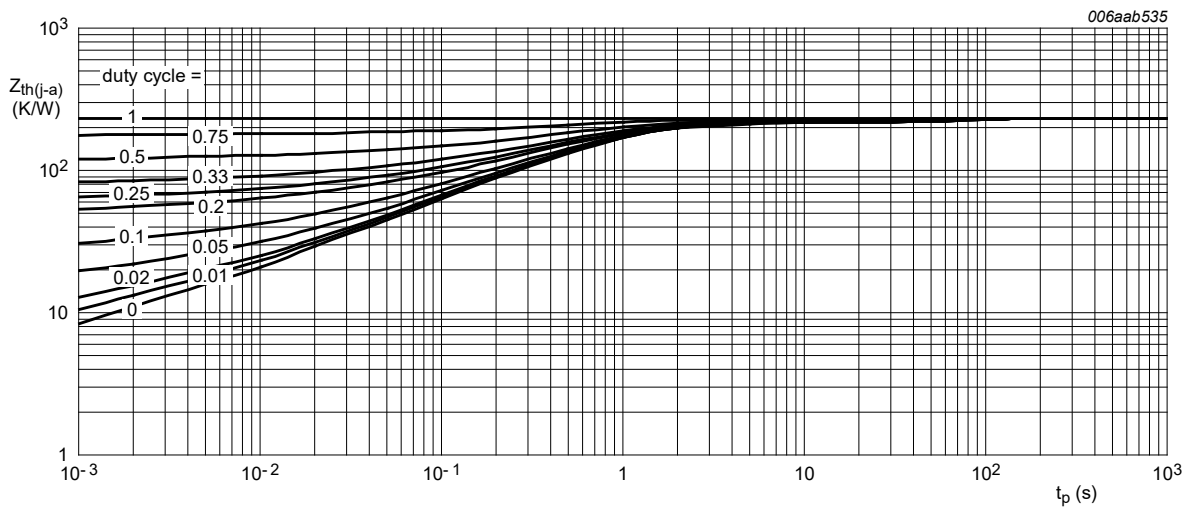


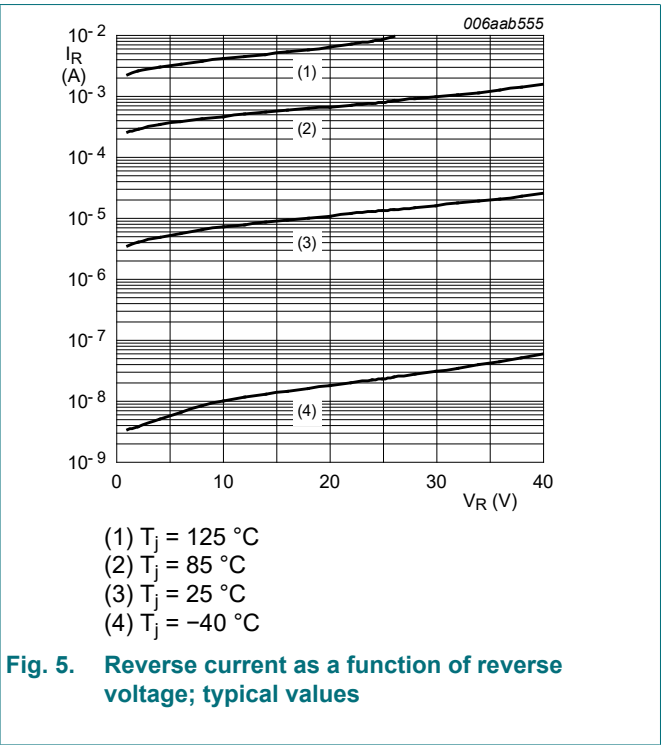
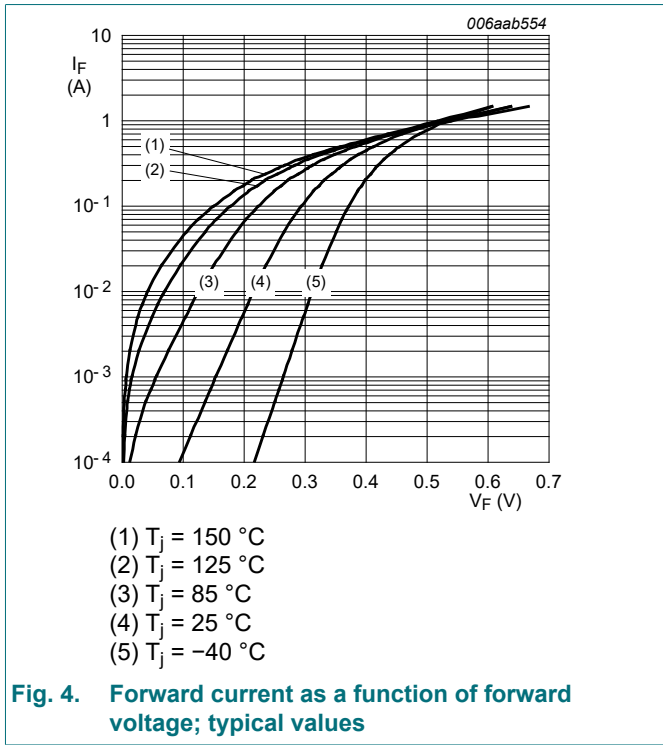
Fig. 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

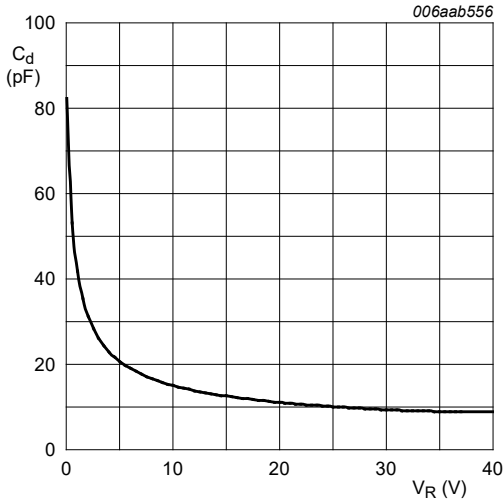
### 10. Characteristics

**Table 7. Characteristics**

$T_{amb} = 25\text{ }^{\circ}\text{C}$  unless otherwise specified.

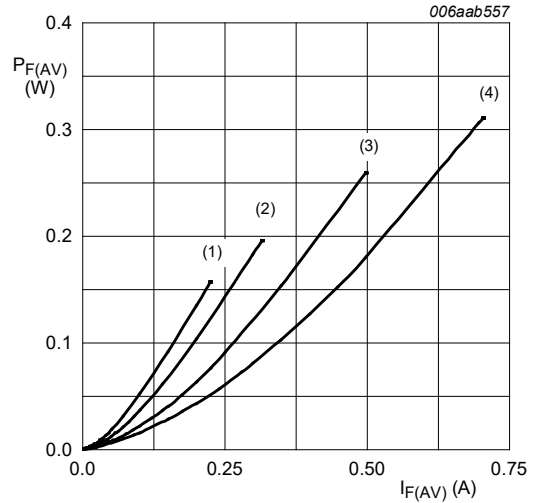
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Per diode</b>						
$V_F$	forward voltage	$I_F = 0.1\text{ mA}; T_j = 25\text{ }^{\circ}\text{C}$	-	95	130	mV
		$I_F = 1\text{ mA}; T_j = 25\text{ }^{\circ}\text{C}$	-	155	210	mV
		$I_F = 10\text{ mA}; T_j = 25\text{ }^{\circ}\text{C}$	-	220	270	mV
		$I_F = 100\text{ mA}; T_j = 25\text{ }^{\circ}\text{C}$	-	295	350	mV
		$I_F = 500\text{ mA}; T_j = 25\text{ }^{\circ}\text{C}$	-	410	470	mV
$I_R$	reverse current	$V_R = 10\text{ V}; T_j = 25\text{ }^{\circ}\text{C}$	-	7	20	$\mu\text{A}$
		$V_R = 40\text{ V}; T_j = 25\text{ }^{\circ}\text{C}$	-	27	100	$\mu\text{A}$
$C_d$	diode capacitance	$V_R = 1\text{ V}; f = 1\text{ MHz}; T_j = 25\text{ }^{\circ}\text{C}$	-	43	50	pF
$t_{rr}$	reverse recovery time	$I_F = 10\text{ mA}; I_R = 10\text{ mA}; I_{R(\text{meas})} = 1\text{ mA}; R_L = 100\text{ }\Omega; T_j = 25\text{ }^{\circ}\text{C}$	-	13	-	ns





$f = 1 \text{ MHz}; T_{\text{amb}} = 25 \text{ }^\circ\text{C}$

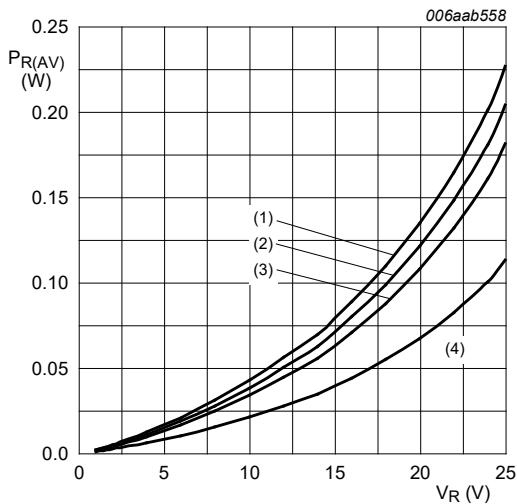
**Fig. 6. Diode capacitance as a function of reverse voltage; typical values**



$T_j = 150 \text{ }^\circ\text{C}$

- (1)  $\delta = 0.1$
- (2)  $\delta = 0.2$
- (3)  $\delta = 0.5$
- (4)  $\delta = 1$

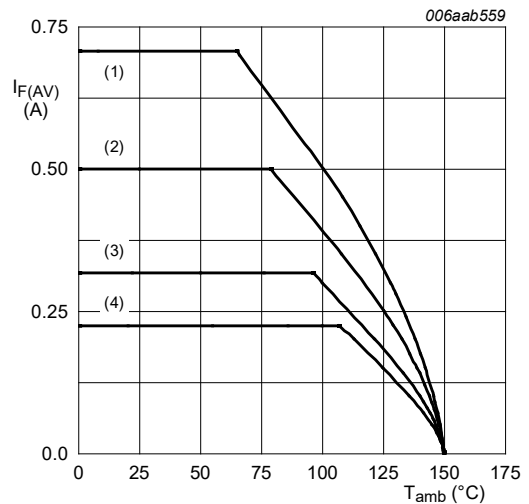
**Fig. 7. Average forward power dissipation as a function of average forward current; typical values**



$T_j = 125 \text{ }^\circ\text{C}$

- (1)  $\delta = 1$
- (2)  $\delta = 0.9$
- (3)  $\delta = 0.8$
- (4)  $\delta = 0.5$

**Fig. 8. Average reverse power dissipation as a function of reverse voltage; typical values**

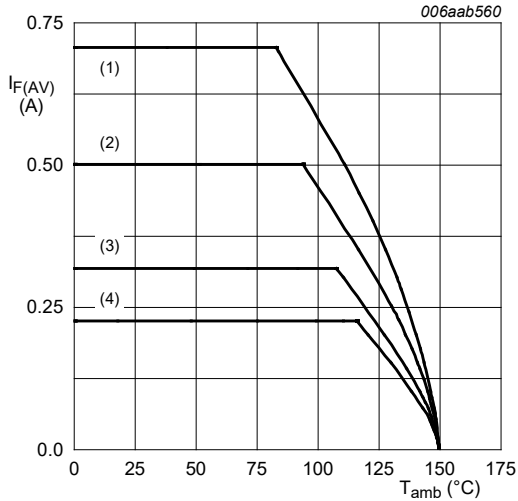


FR4 PCB, standard footprint

$T_j = 150 \text{ }^\circ\text{C}$

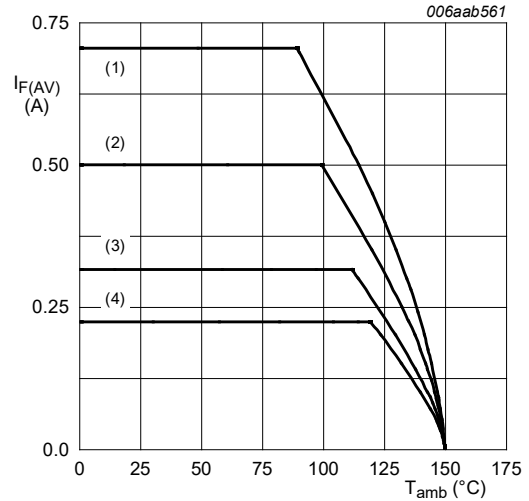
- (1)  $\delta = 1; \text{DC}$
- (2)  $\delta = 0.5; f = 20 \text{ kHz}$
- (3)  $\delta = 0.2; f = 20 \text{ kHz}$
- (4)  $\delta = 0.1; f = 20 \text{ kHz}$

**Fig. 9. Average forward current as a function of ambient temperature; typical values**



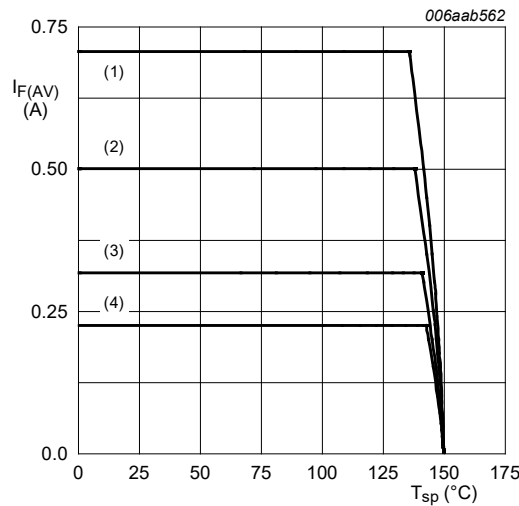
FR4 PCB, mounting pad for cathode 1 cm<sup>2</sup>  
 $T_j = 150\text{ °C}$   
 (1)  $\delta = 1$ ; DC  
 (2)  $\delta = 0.5$ ;  $f = 20\text{ kHz}$   
 (3)  $\delta = 0.2$ ;  $f = 20\text{ kHz}$   
 (4)  $\delta = 0.1$ ;  $f = 20\text{ kHz}$

Fig. 10. Average forward current as a function of ambient temperature; typical values



Ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint  
 $T_j = 150\text{ °C}$   
 (1)  $\delta = 1$ ; DC  
 (2)  $\delta = 0.5$ ;  $f = 20\text{ kHz}$   
 (3)  $\delta = 0.2$ ;  $f = 20\text{ kHz}$   
 (4)  $\delta = 0.1$ ;  $f = 20\text{ kHz}$

Fig. 11. Average forward current as a function of ambient temperature; typical values



$T_j = 150\text{ °C}$   
 (1)  $\delta = 1$ ; DC  
 (2)  $\delta = 0.5$ ;  $f = 20\text{ kHz}$   
 (3)  $\delta = 0.2$ ;  $f = 20\text{ kHz}$   
 (4)  $\delta = 0.1$ ;  $f = 20\text{ kHz}$

Fig. 12. Average forward current as a function of solder point temperature; typical values

### 11. Test information

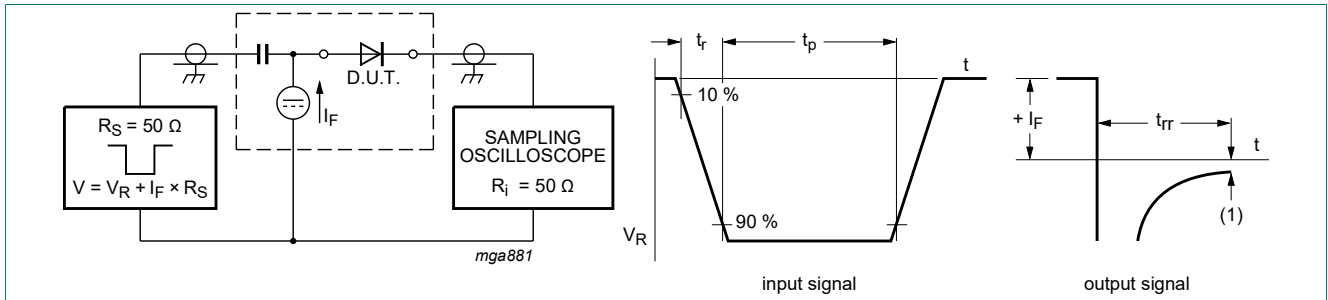


Fig. 13. Reverse recovery time: test circuit and waveforms

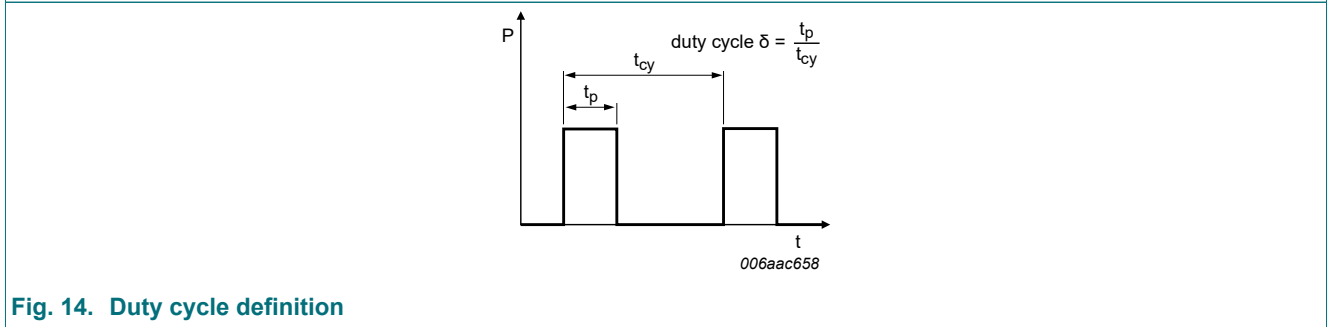


Fig. 14. Duty cycle definition

The current ratings for the typical waveforms are calculated according to the equations:  
 $I_{F(AV)} = I_M \times \delta$  with  $I_M$  defined as peak current,  $I_{RMS} = I_{F(AV)}$  at DC, and  $I_{RMS} = I_M \times \sqrt{\delta}$  with  $I_{RMS}$  defined as RMS current.

#### Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

### 12. Package outline

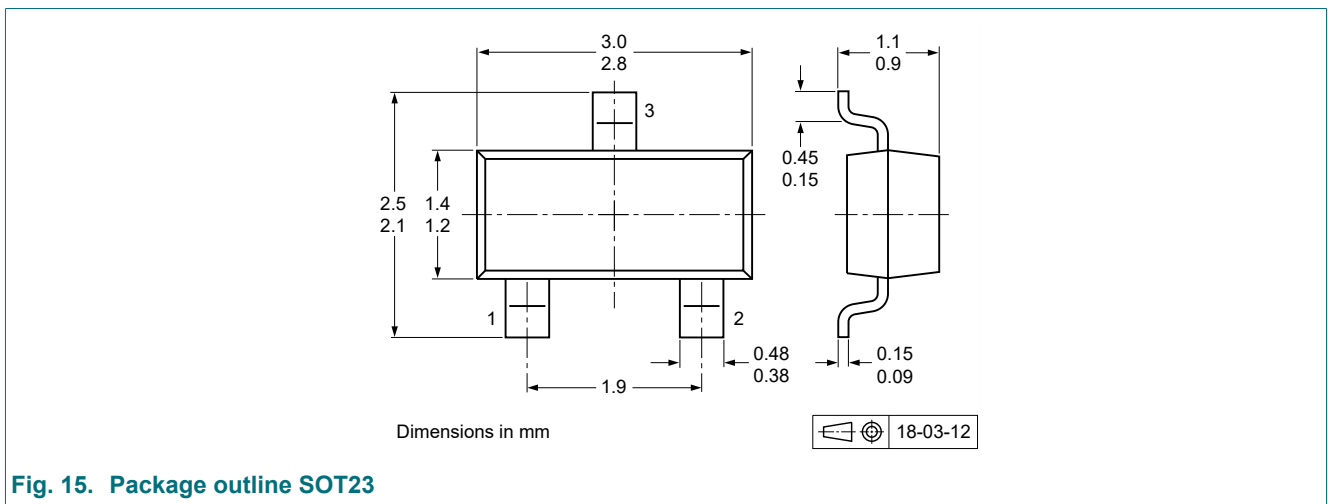


Fig. 15. Package outline SOT23



### 13. Soldering

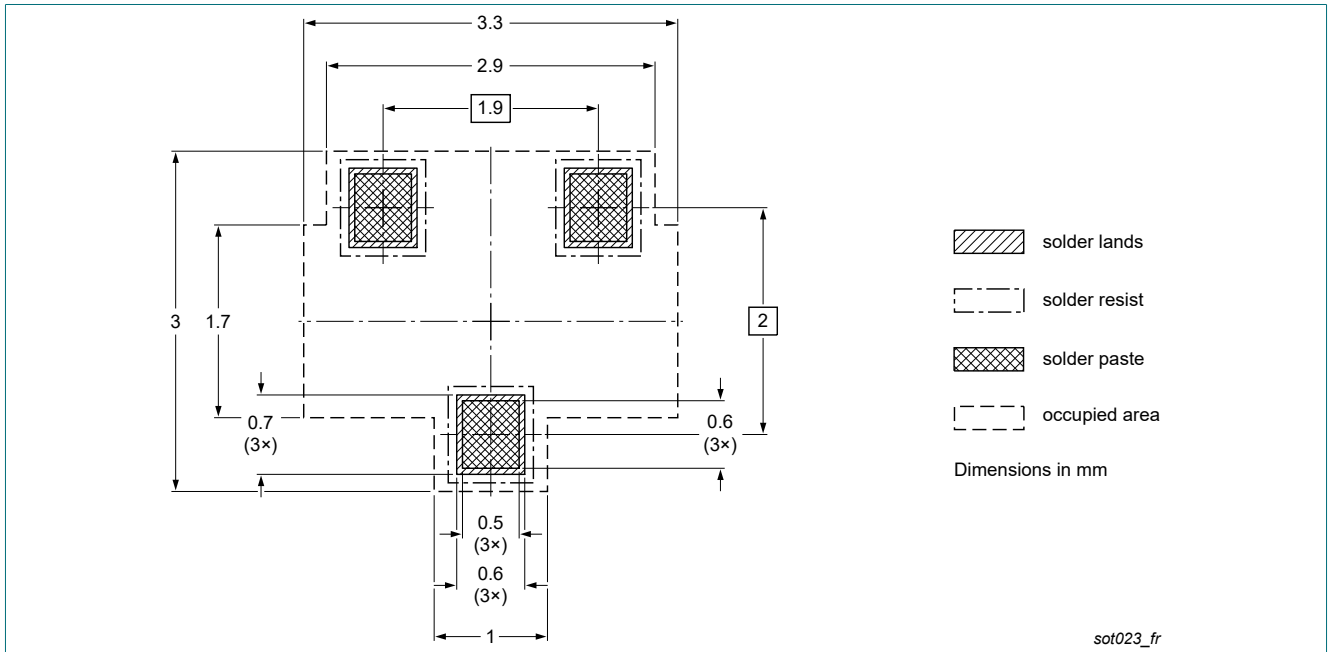


Fig. 16. Reflow soldering footprint for SOT23

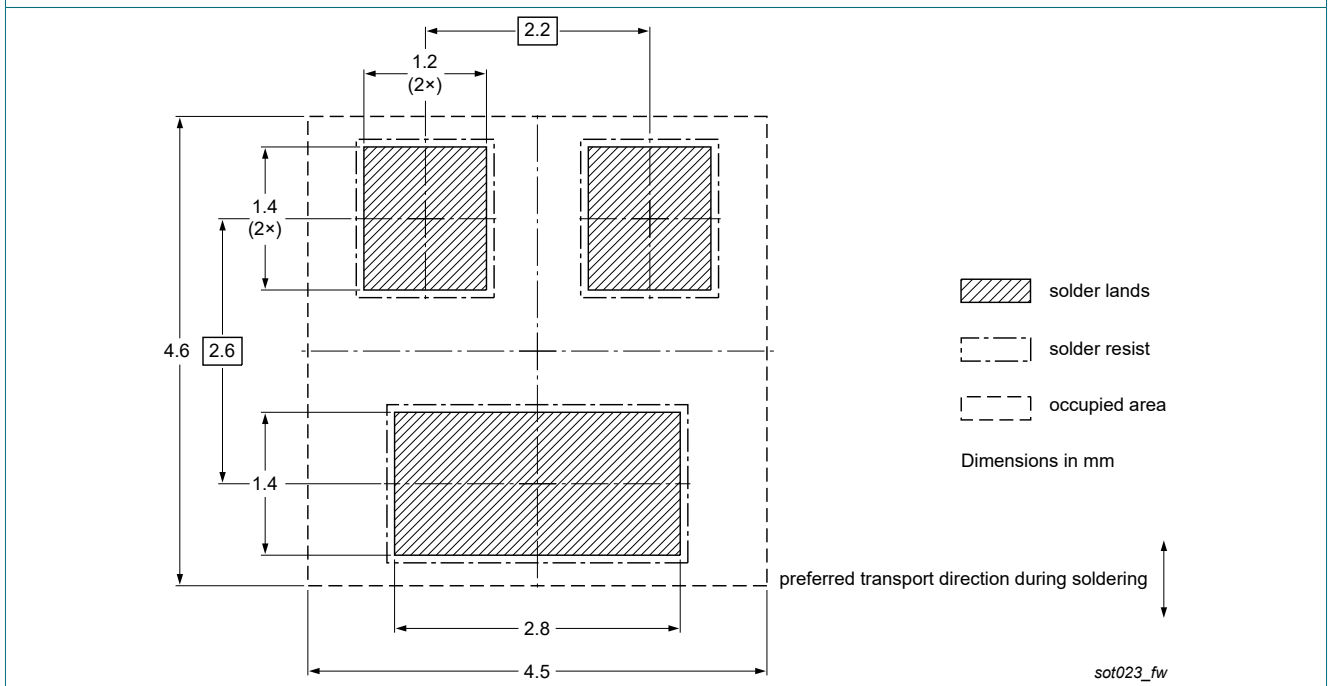


Fig. 17. Wave soldering footprint for SOT23

## 14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PMEG4005CT v.3	20190924	Product data sheet	-	PMEG4005CT v.2
Modifications:	<ul style="list-style-type: none"><li>The format of this data sheet has been redesigned to comply with the identity guidelines of Nexperia.</li><li>Legal texts have been adapted to the new company name where appropriate.</li></ul>			
PMEG4005CT v.2	20100920	Product data sheet	-	PMEG4005CT v.1
PMEG4005CT v.1	20090605	Product data sheet	-	-

## 15. Legal information

### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
- [3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the internet at <https://www.nexperia.com>.

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Date of release: 24 September 2019

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